

Page 56, line 14, change "Example 5" to --Example 9--.

Page 57, line 16, change "(G)" to --(M)--.

In the Claims:

Please amend claims 4-8, 10, 15-17 and 19 as follows:

Claim 4, line 2, delete "or 2".

Claim 5, line 2, delete "or 2".

Claim 6, line 2, delete "or 2".

Claim 7, line 2, delete "or 2".

Claim 8, line 2, delete "or 2".

Claim 10, line 2, delete "or 2".

Claim 15, line 2, delete "or 2".

16. (Amended) An adhesive film for semiconductor parts, which is obtained by forming a film from the adhesive according to Claim 1 [any one of Claims 1 to 15].

17. (Amended) A semiconductor part package obtained by bonding a semiconductor part to a substrate with a solution or film of the adhesive according to Claim 1 [any one of Claims 1 to 15].

19. (Amended) A process for producing a semiconductor part package, which comprises applying a solution of the adhesive according to Claim 1 [any one of Claims 1 to 15] to the surface of a substrate, drying a solvent to form an adhesive layer, placing a semiconductor part on the adhesive layer, bonding the semiconductor part to the substrate by heating and pressurizing the adhesive layer at a temperature not lower than the glass transition